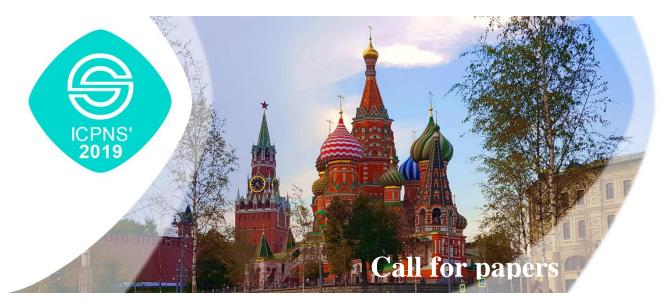
The 9th International Conference on Physical and Numerical Simulation of Materials Processing



October 10-14 Moscow, Russia

The 9th International Conference Physical and Numerical on Simulation of Materials Processing (ICPNS'2019) follows in USA (Seattle-2016), Finland (Oulu-2013) China and (Guilin 2010, Zhengzhou-2007, Shanghai-2004, Beijing-1999, Hainan-1997, Harbin-1990) and provides a forum for researchers around the world to present papers on recent advances in the overall field of physical & numerical methods and their applications in materials processing and testing.

ORGANIZED BY

Tikhonov Moscow Institute of Electronics and Mathematics of National Research University Higher School of Economics

International Federation on Physical and Numerical Simulation of Materials Processing (IFPNS)

https://icpns2019.hse.ru

Moscow, Russia

SCOPE AND TOPICS

The conference will cover all aspects of Physical and Numerical Simulation of Materials Processing. The focus will be on (but not limited to) the following topics:

- 1. Physical simulation of forming operations and thermo-mechanical processing of materials
- 2. Design and optimization of materials processing technologies
- 3. Mathematical and numerical modeling of materials constitutive behavior
- 4. Atomistic and multiscale computer simulation
- 5. Materials characterization
- 6. Radiation, microwave and laser processing of materials
- 7. Nondestructive testing
- 8. Intelligent manufacturing
- 9. Modelling and simulation in metallurgical processing
- 10. Software engineering and software development for materials processing, computation and design
- 11. Additive manufacturing, processes and materials
- 12. Simulation of phase transformations and microstructural evolution
- 13. Material design approaches and experiences, computation material science and molecular dynamics simulation
- 14. Sustainability through materials processing and waste valorization

IMPORTANT DATES

Abstract submissions due: April 15, 2019
Deadline for full manuscript submission: Final program on the website: April 15, 2019
May 10, 2019
September 30, 2019

- Dates of the conference: October 10-14, 2019

PUBLICATION

All accepted abstracts will be printed in the proceedings of ICPNS'2019.

Full manuscripts after peer review will be published in <u>Procedia Manufacturing</u>, an open access Elsevier journal available in <u>ScienceDirect.com</u> and indexed in world leading scientific databases including **Scopus** and **Web of Science**.

SOCIAL PROGRAM

During the conference, the organization committee will arrange a tour program for participants and companions to visit most popular attractions in Moscow.

A one day trip to St. Petersburg will be organized as an optional activity (for additional payment), including visiting Peter the Great St. Petersburg Polytechnic University (SPbPU).

Moscow, Russia

CONFERENCE FEES

	Early bird Before May 31, 2019	Standard Before July 15, 2019
Regular participant ¹ Accommodation in double room	700 USD	800 USD
Regular participant ² Accommodation in single room	900 USD	1000 USD
Regular participant without accommodation	500 USD	600 USD
Student without accommodation	350 USD	600 USD
Accompanying person	350 USD	450 USD

Participant fee includes:

- Accommodation in the conference (double¹ or single² room),
- Access to Plenary Session, Parallel Sessions, Poster Session and Exhibition
- Participant bag, book of abstracts and conference program
- Lunch & coffee breaks during the conference
- Social program, welcome reception, conference diner
- Certificate of participation

Accompanying person fee includes:

- Accommodation in the conference hotel (double room)
- Social program, welcome reception, conference diner

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